

Special Issue

Advancements in Low-Dimensional Materials: Focus on Detailed Methodologies

Message from the Guest Editors

Low-dimensional materials exhibit a wide range of new properties that can be employed to fabricate improved and novel devices. The ongoing research on these materials is advancing electronics, materials science, and related fields. We would like you to consider submitting a manuscript in this field that provides detailed and rigorous methodologies or processes, as these are crucial for advancing the field and ensuring replicability and robustness in research findings.

Guest Editors

Dr. Sake Wang

Dr. Nguyen Tuan Hung

Dr. Minglei Sun

Deadline for manuscript submissions

25 September 2025



Processes

an Open Access Journal
by MDPI

Impact Factor 2.8
CiteScore 5.5



mdpi.com/si/214337

Processes
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
processes@mdpi.com

[mdpi.com/journal/
processes](https://mdpi.com/journal/processes)





Processes

an Open Access Journal
by MDPI

Impact Factor 2.8
CiteScore 5.5



[mdpi.com/journal/
processes](https://mdpi.com/journal/processes)



About the Journal

Message from the Editor-in-Chief

You are invited to contribute either a research article or a comprehensive review for consideration and publication in *Processes* (ISSN 2227-9717). *Processes* is published in open access format – research articles, reviews, and other content are released on the internet immediately after acceptance. The scientific community and the general public have unlimited, free access to the content. As an open access journal, *Processes* is supported by the authors and their institutes through the payment of article processing charges (APCs) for accepted papers. We would be pleased to welcome you as one of our authors.

Editor-in-Chief

Prof. Dr. Giancarlo Cravotto

Department of Drug Science and Technology, University of Turin, Via P. Giuria 9, 10125 Turin, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, AGRIS, and other databases.

Journal Rank:

CiteScore - Q2 (Chemical Engineering (miscellaneous))